PATENT

Docket No. JCLA7749

Page 1



ASSISTANT COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

ATTENTION: APPLICATION BRANCH

Sin

Transmitted herewith for filing is the patent application of Inventors; James Seng-Ju Ni

For: CIRCUIT TRIMMING OF PACKAGED IC CHIP

Enclosed are:

Specification 14 pages.

Sheets of drawings

 Sheets of drawings

 ■ 3

Recordation Form Cover sheet with _2_ pages assignment.

□ A certified copy of Taiwan Patent Application No. __ dated __.

 SIGNED declaration and power of attorney.

Return Prepaid postcard.

CLAIMS AS FILED							
FOR	NUMB	ER FU	ED	NUMB	ER EXTR	A RATE	FEE
Basic Fee						\$370.00	\$370.00
Total Claims	20	_	20 =	= 0	×	\$9.00	\$0.00
Independent Claims	4	_	3 =	: 1	×	\$42.00	\$42.00
If application contains any multiple dependent claim (s), then add						\$140.00	\$0.00
TOTAL FILING FEE							\$412.00

A check in the amount of \$412.00 cover the filing fee is enclosed.

A check in the amount of \$40.00 to cover the assignment recording fee.

A duplicate copy of this sheet is enclosed.

Applicant claims small entity status. See 37 CFR 1.27

Jiawei Huang

Registration No. 43,330

CLATT SCHOOLS

J.C. PATENTS, INC.

4 VENTURE, SUITE 250 IRVINE, CALIFORNIA 92618 (949) 660-0761 FAX: (949) 660-0809

Assistant Commissioner for Patents Washington, D.C. 20231

CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Docket No.

2. JCLA7749

Applicant(s)

3. James Seng-Ju Ni

For

4. CIRCUIT TRIMMING OF PACKAGED IC CHIP

"Express Mail"

5. EL 857833502 US

Mailing Label No.

Date of Deposit : November 21, 200/

I hereby certify that the accompanying

Transmittal in Duplicate; Specification <u>14 pages</u>, <u>3</u> sheets of drawings; **SIGNED**Declaration and Power of Attorney <u>2</u> pages; Recordation Form Cover Sheet and
Assignment <u>3</u> pages; Checks for Filing Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

M. Chang Michelle Chang